

WHAT IS CLAIMED IS:

1. A microactuator device having a cut face formed by cutting, wherein said cut face is subjected to anti-release treatment for preventing release of particles produced by cutting.
2. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by baking an entire surface of said microactuator device including said cut face to form a sintered image after cutting into a final product shape.
3. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by polishing an entire surface of said microactuator device including said cut face formed by cutting after baking.
4. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by reheating an entire surface of said microactuator device including said cut face formed by cutting after baking to thereby refix said particles to said entire surface.
5. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by exclusively heating said cut face formed by cutting after baking to thereby refix said particles to said cut face.
6. A microactuator device according to claim 2, wherein said anti-release treatment is followed by washing of an entire surface of said microactuator device including said cut face to remove said particles.
7. A microactuator device according to claim 3, wherein said anti-release treatment is followed by washing of an entire surface of said microactuator device including said cut face to remove said particles.

8. A microactuator device according to claim 4, wherein said anti-release treatment is followed by washing of an entire surface of said microactuator device including said cut face to remove said particles.
9. A microactuator device according to claim 5, wherein said anti-release treatment is followed by washing of an entire surface of said microactuator device including said cut face to remove said particles.
10. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by coating said cut face formed by cutting after baking with a glass to avoid exposure of said cut face.
11. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by coating an entire surface of said microactuator device including said cut face formed by cutting after baking with a flexible resin material which hardly suppresses the displacement of said microactuator device.
12. A microactuator device according to claim 1, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.
13. A microactuator device according to claim 2, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.

14. A microactuator device according to claim 3, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.

15. A microactuator device according to claim 4, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.

16. A microactuator device according to claim 5, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.

17. A microactuator device according to claim 7, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.

18. A microactuator device according to claim 8, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.

19. A microactuator device according to claim 6, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which includes said cut face.

20. A microactuator device according to claim 7, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which includes said cut face.
21. A microactuator device according to claim 8, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which includes said cut face.
22. A microactuator device according to claim 9, wherein said microactuator device comprises a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which includes said cut face.